

Features

- 1808 0.55mm SMD LED
- High Brightness
- AllnGaP Technology
- Small package
- High reliability

Applications

- Consumer Electronics
- Wearable
- Automobile After Market
- Industrial Equipment

Description

The IN-P18ATR is a popular low profile 1808 package with versatile design capabilities. It is a PLCC type silicone style LED which can be used in various applications.

Recommended Solder Pattern

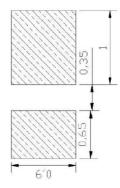
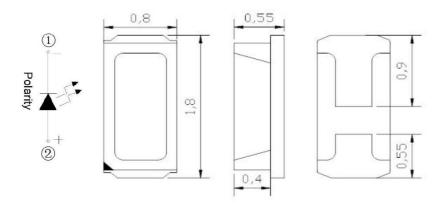


Figure 1. IN-P18ATR Solder Pattern

Package Dimensions in mm



Notes.

- All dimensions are in millimeters.
- 2. Tolerance is ± 0.10 mm unless otherwise noted

Figure 2. IN-P18ATR Package Dimensions



Absolute Maximum Rating at 25°C (Note 1)

Product	Emission Color	P _d (mW)	I _F (mA)	I _{FP} * (mA)	V _R (V)	T _{OP} (°C)	T _{ST} (°C)
IN-P18ATR	Red	65	25	100	5	-30°C~+85°C	-40°C~+90°C

Notes

1. Condition for IFP is pulse of 1/10 duty and 0.1msec width

ESD Precaution

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AllnGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).



Electrical Characteristics $T_A = 25\%$ (Note 1)

		V _F (V)		λ(nm)			Viewing Angle	I* _v (mcd)	
Product	Emission Color	I _F (mA)	min	max	λ_{D}	$\lambda_{ extsf{P}}$	Δλ	2θ1/2	typ.
IN-P18ATR	Red	20	1.8	2.6	620	630	20	120	230

Notes

Luminous Intensity (mcd) Bin:

Bin	Luminous Intensity (mcd)					
	Minimum	Maximum				
M1	180	230				
M2	230	285				
N1	285	350				
N2	350	450				

@20mA / Ta=25° C, Tolerance: ±15%

Wavelength (nm) Bin:

Color	Bin Code	Spec. Range
	Α	615-620 nm
Red	В	620-625 nm
	С	625-630 nm

@20mA / Ta=25°C, Tolerance: ±1.0nm

Forward Voltage (VF) Bin:

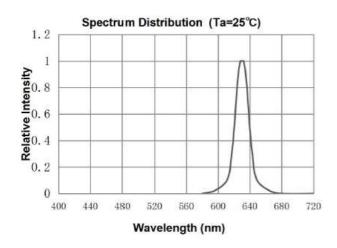
Color	Bin Code	Spec. Range
	1	1.8-2.0 V
Red	2	2.0-2.2 V
neu	3	2.2-2.4 V
	4	2.4-2.6 V

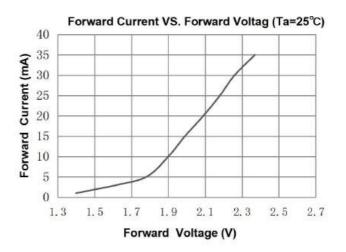
@20mA / Ta=25 $^{\circ}$ C, Tolerance: ±0.1 V

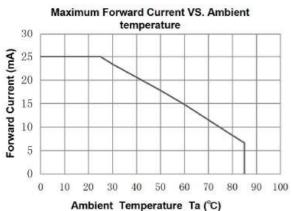
^{1.} Performance guaranteed only under conditions listed in above tables.

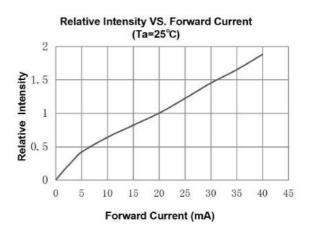


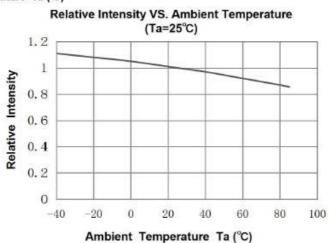
Typical Characteristic Curves





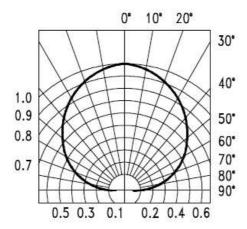








Typical Characteristic Curves – Radiation Pattern



Ordering Information

Product	Emission Color	Technology	Test Current I _F (mA)	Luminous Intensity Iv (mcd) (Typ.)	Forward Voltage V _F (V) (Typ.)	Orderable Part Number
IN-P18ATR	Red	AllnGaP	20	230	2.2	IN-P18ATR



Label Specifications



Inolux P/N:

ı	N	-	Р	1	8	Α	Т			R	-		
			Material	Pacl	kage	Variation	Orientation	Current	Lens	Color		Custor Stamp	
Ir	olux		P = PLCC Type	18A =	: 1.8 x C	1.8 x 0.55mm	T = Top Mount	(Blank) = 20mA	(Blank) = Clear U = Diffused	R=620nm		-	

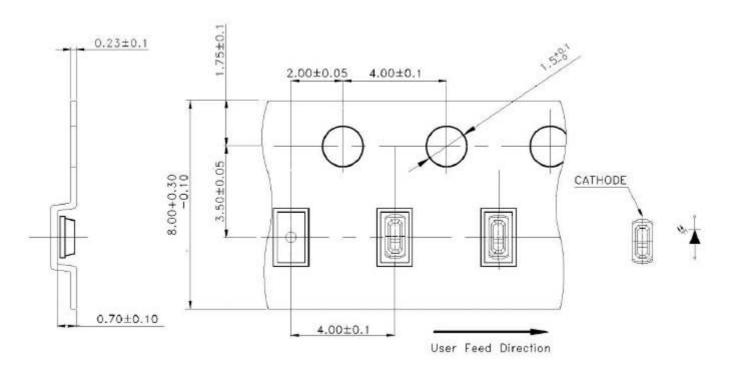
Lot No.:

Z	2	0	1	7	01	24	001
Internal Year (2017, 2018,)					Month	Date	Serial
Tracker		rear (2017	, 2010,)		IVIOITUI	Date	Serial

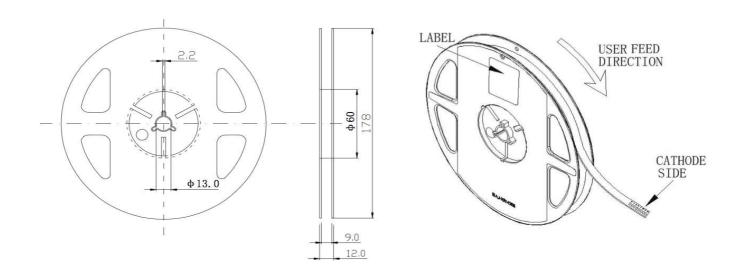


Packaging Information: 4000pcs Per Reel

Tape Dimension

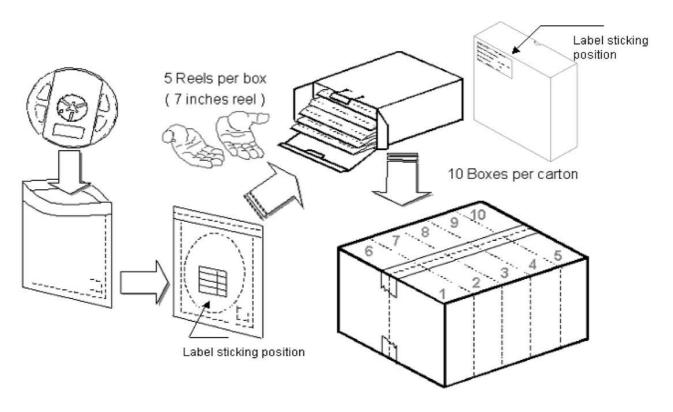


Reel Dimension





Packing Dimension



5 boxes per carton are available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	4000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	IN standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	IN standard	Paper	Non-specified
O.1			

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of lv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

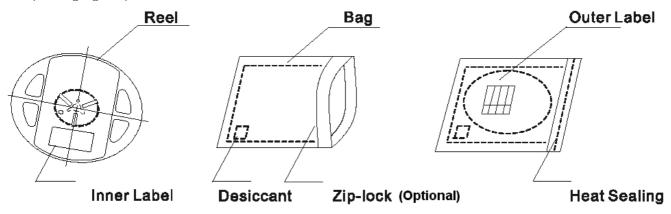


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

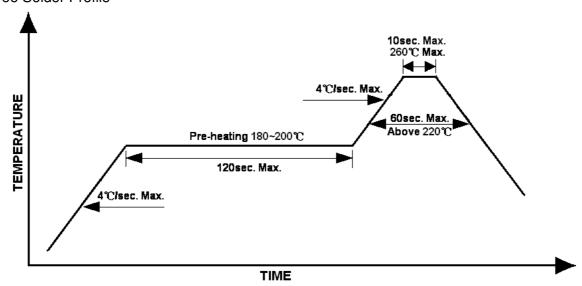
The packaging sequence is as follows:



Reflow Soldering

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

Lead-free Solder Profile





Precautions

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.



IN-P18ATR Top View SMD LED 1808 PLCC2

Reliability

Chability	Te (1	0	To 11:1		
Item	Frequency/ lots/ samples/ failures	Standards Reference	Conditions		
Precondition	For all reliability monitoring tests according to JEDEC Level 2	J-STD-020	1.) Baking at 85°C for 24hrs2.) Moisture storage at 85°C/60% R.H. for 168hrs		
Solderability	1Q/ 1/ 22/ 0	JESD22-B102-B And CNS-5068	Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s		
Resistance to soldering heat		CNS-5067	Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s		
Operating life test	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs		
High humidity, high temperature bias	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs		
High temperature bias	1Q/ 1/ 20	IN specs.	Tamb: 55°C IF=20mA Duration: 1000hrs		
Pulse life test	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)		
Temperature cycle	1Q/ 1/ 76/ 0	JESD-A104-A IEC 68-2-14, Nb	A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type		
High humidity storage test	1Q/ 1/ 40/ 0	CNS-6117	60+3°C 90+5/-10% R.H. for 500hrs		
High temperature storage test	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs		
Low temperature storage test	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs		



Revision History

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	05-12-2021

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